

THIN FILM DEPOSITION APPARATUS FOR SEMICONDUCTOR**Abstract of the Disclosure**

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A semiconductor thin film deposition apparatus having at least one reactor in which a wafer is received, a gas supply portion for supplying a reaction gas or inert gas to the reactor, and an exhaust pump for exhausting gas from the reactor, characterized in that the improvement comprises an ozone supply portion for generating ozone as a gas that reacts with the reaction gas, and for supplying the ozone to the reactor.

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Figure 1.